

SOT-227 AC Switch Full Controlled Thyristor Power Module, 60 A, 1600 V



SOT-227

PRIMARY CHARACTERISTICS					
V _{RRM} / V _{DRM}	1600 V				
V _{TM} (typical) at 60 A, 25 °C	1.2 V				
I _{T(AV)} , T _C = 110 °C	60 A				
T _{VJ}	150 °C				
T _{operative}	125 °C				
Package	SOT-227				
Circuit	Two thyristors, back to back				

FEATURES

- · High voltage
- Industrial standard package
- Low thermal resistance
- UL pending
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- Excellent thermal performances
- High surge capability
- Easy mounting on heatsink
- Thyristor for line frequency

APPLICATIONS

Line rectifying 50 Hz / 60 Hz

- Softstart AC motor control
- DC motor control
- Power converter
- AC power control
- Lighting and temperature control

MAJOR RATINGS AND CHARACTERISTICS (T _J max. 150 °C)						
SYMBOL	DL CHARACTERISTICS VALUES		UNITS			
I _{T(AV)}	110 °C	60				
1	50 Hz	850	А			
I _{TSM}	60 Hz	890				
l ² t	50 Hz	3.6	kA ² s			
	60 Hz	3.3	KA-S			
I²√t		36.1	kA²√s			
V _{RRM} / V _{DRM}		1600	V			
T _{op}	Operating temperature	-40 to +125				
T _{Stg}		-40 to +150	°C			
TJ	Virtual junction temperature	-40 to +150				

ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS							
V _{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V	I _{RRM,} I _{DRM} AT 125 °C mA				
1600	1700	1600	25				



ON-STATE CONDUCTION						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS	
Maximum average on-state current (thyristors)	I _{T(AV)}	180° conduction, half sine wave, T _C = 110 °C		60		
		t = 10 ms	No voltage		850	
Maximum peak, one-cycle non-repetitive		t = 8.3 ms	reapplied	Sinusoidal	890	Α
on-state	I _{TSM}	t = 10 ms	100 % V _{RRM}	half wave, initial $T_J = 150 ^{\circ}\text{C}$	715	
		t = 8.3 ms	reapplied		748	
		t = 10 ms	No voltage		3.6	
Maximum 12t for fusing	l ² t	t = 8.3 ms	reapplied	Initial T 150 °C	3.3	kA ² s
Maximum I ² t for fusing	1-1	t = 10 ms	100 % V _{RRM}	Initial $T_J = 150 ^{\circ}\text{C}$	2.5	
		t = 8.3 ms	reapplied		2.3	
Maximum I²√t for fusing	I ² √t (1)	t = 0.1 ms to 10 ms, no voltage reapplied		36.1	kA²√s	
Maximum I-VE for fusing	1- ([(.)	$T_J = T_J$ maximum				
Maximum value or threshold voltage	V _{T(TO)} (2)	Low level (3)	T _J = 150 °C		0.89	V
iviaximum value or tilleshold voltage		High level ⁽⁴⁾			1.02	
Maximum value of on-state slope resistance	r _t ⁽²⁾	Low level (3)	T _J = 150 °C		9.17	mΩ
iviaximum value of on-state slope resistance		High level (4)			9.01	
Maximum peak on-state voltage	.,,	I _{TM} = 60 A	T _J = 25 °C		1.50	V
iviaximum peak on-state voitage	V _{TM}	$T_{\rm J} = 150 {\rm ^{\circ}C}$			1.41	v
Maximum non-repetitive rate of rise of	dl/dt	T _J = 125 °C, I _T = 100 A, I _{at} = 450 mA, V _{GT} = 2.5 V		500	A/µs	
turned on current	ui/ut	1J = 123 O, IT = 100 A, Igt = 430 IIIA, VGT = 2.3 V		300	-7ν μδ	
Maximum holding current	I _H	$T_J = 25$ °C, anode supply = 6 V,		200	mA	
-	resistive load, gate ope		open circuit			
Maximum latching current	ΙL	T _J = 25 °C, anode supply = 6 V, resistive load		400		

Notes

- (1) I^2t for time $t_x = I^2\sqrt{t} \ x \ \sqrt{t_x}$
- $^{(2)}$ Average power = $V_{T(TO)} \; x \; I_{T(AV)} + r_t \; x \; (I_{T(RMS)})^2$
- (3) 16.7 % $\times \pi \times I_{AV} < I < \pi \times I_{AV}$
- $^{(4)}~I>\pi~x~I_{AV}$

TRIGGERING					
PARAMETER	SYMBOL		TEST CONDITIONS		UNITS
Maximum peak gate power	P_{GM}	10 ms sine p	oulse, no voltage reapplied	10	W
Maximum average gate power	P _{G(AV)}			2.5	VV
Maximum peak gate current	I _{GM}			2.5	Α
Maximum peak negative gate voltage	-V _{GM}			10	
		T _J = -40 °C		1.6	V
Maximum gate voltage required to trigger	V_{GT}	T _J = 25 °C	Anode supply = 6 V resistive load	1.5	V
		T _J = 150 °C		1	
		T _J = -40 °C		150	
Maximum gate current required to trigger	I _{GT}	T _J = 25 °C	Anode supply = 6 V resistive load	100	mA
		T _J = 150 °C		45	
Maximum gate voltage that will not trigger	V_{GD}	T _J = 150 °C, 67 % V _{DRM} applied		0.2	V
Maximum gate current that will not trigger	I_{GD}	T _J = 150 °C, 67 % V _{DRM} applied		5	mA

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum peak reverse and off-state leakage current at V _{RRM} , V _{DRM}	I _{RRM,} I _{DRM}	T _J = 125 °C, gate open circuit	25	mA	
Maximum RMS insulation voltage	V _{INS}	50 Hz	2500 (1 min)	V	
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = 150 ^{\circ}\text{C}$, linear to 0.67 V_{DRM}	1000	V/µs	



THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL TEST CONDITIONS		VALUES	UNITS
Maximum internal thermal resis junction to case per leg	tance,	R _{thJC}	DC operation	0.29	°C/W
Typical thermal resistance, case to heat sink per module		R _{thCS}	Mounting surface flat, smooth and greased	0.1	C/VV
Mounting torque ± 10 %	to heat sink		A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound.	1.3	Nm
Approximate weight				30	g
Case style				SOT	-227

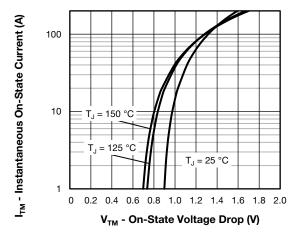


Fig. 1 - I_{TM} vs. V_{TM} (On-State Voltage Drop Characteristics)

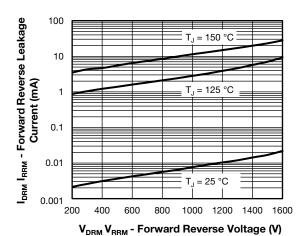


Fig. 2 - I_{DRM} I_{RRM} vs. V_{DRM} V_{RRM} (Forward Reverse Leakage Current)

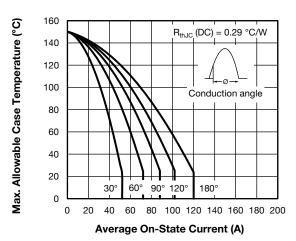


Fig. 3 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)

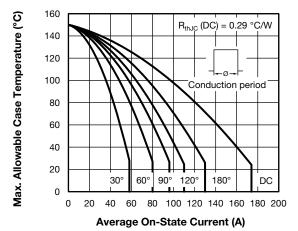


Fig. 4 - Maximum Allowable Case Temperature vs. Average On-State Current (Current Rating Characteristics)

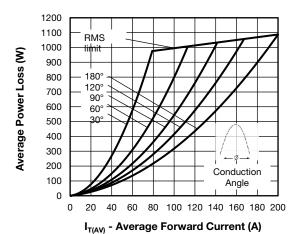


Fig. 5 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)

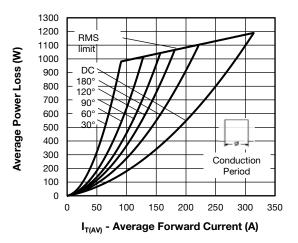
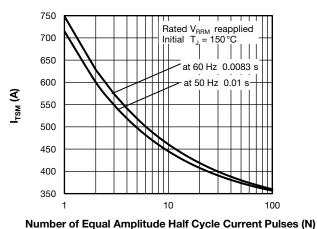
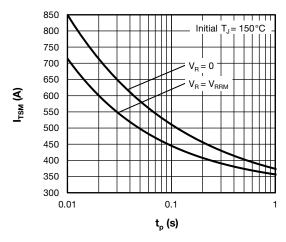


Fig. 6 - Average Power Loss vs. Average Forward Current (Forward Power Loss Characteristics)



Number of Equal Amplitude Hall Cycle Current Pulses (N)

 $\label{eq:Fig. 7-l} {\rm Fig.~7-l_{TSM}~vs.~N} \\ {\rm (Non-Repetitive~Peak~Forward~Surge~Current~vs.~Number~Pulses)}$



 $\label{eq:Fig. 8-l} \textit{Fig. 8-l}_{TSM} \, \textit{vs. t}_{p} \\ \text{(Non-Repetitive Peak Forward Surge Current vs. Pulse Duration)}$

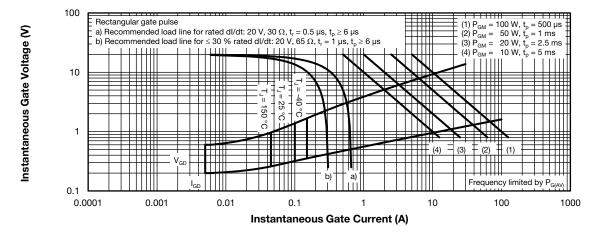


Fig. 9 - Gate Characteristics



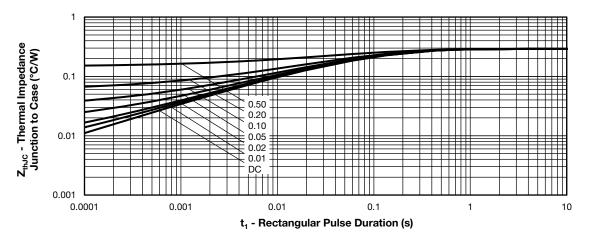
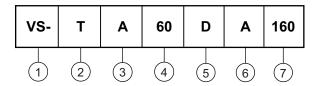


Fig. 10 - Z_{thJC} Thermal Impedance Junction to Case vs. t_1 Rectangular Pulse Duration (Maximum Thermal Impedance Z_{thJC} Characteristics)

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Thyristor dice

Present silicon generation

4 - Rating current

5 - Two thyristors, back to back

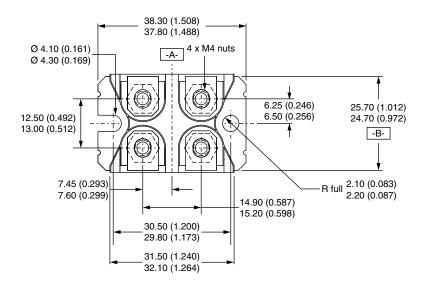
6 - Isolated SOT-227

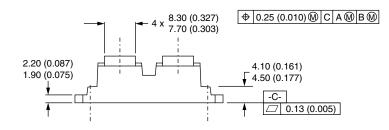
7 - Voltage rating 160 = 1600 V

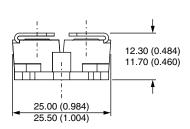
CIRCUIT CONFIGURATION							
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING					
Two thyristors, back to back	D	Lead Assignment 4 4 4 2 2 4 4 4 4 4 4 4 4					

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95423			
Packaging information	www.vishay.com/doc?95425			
Application note	www.vishay.com/doc?95527			

DIMENSIONS in millimeters (inches): **SOT-227 Gen 2**





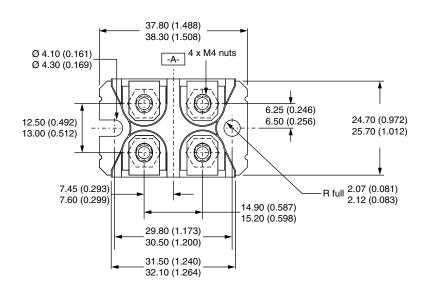


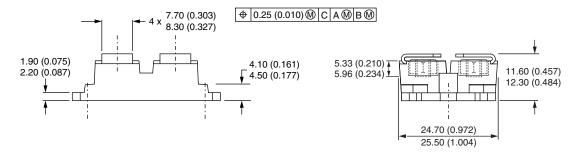
Note

· Controlling dimension: millimeter

SOT-227 Generation 2

DIMENSIONS in millimeters (inches)





Note

· Controlling dimension: millimeter



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